

HPI

TE Internal #: 1-2380320-1 HPI, PCB Mount Header, Wire-to-Board, 11 Position, .059 in [1.5 mm] Centerline, Fully Shrouded, Tin, Surface Mount, Power & Signal, Natural

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Connectors > PCB Connectors > PCB Headers & Receptacles



Connector System: Wire-to-Board

Number of Positions: 11

Number of Rows: 1

Centerline (Pitch): 1.5 mm [.059 in]

Termination Method to Printed Circuit Board: Surface Mount

Features



Product Type Features

| Connector System | Wire-to-Board | |
|---------------------------------------|-----------------------|--|
| Header Type | Fully Shrouded | |
| Sealable | No | |
| Connector & Contact Terminates To | Printed Circuit Board | |
| PCB Connector Assembly Type | PCB Mount Header | |
| Configuration Features | | |
| Number of Positions | 11 | |
| Number of Rows | 1 | |
| Electrical Characteristics | | |
| Termination Resistance | 20 mΩ | |
| Insulation Resistance | 1000 MΩ | |
| Dielectric Withstanding Voltage (Max) | 500 V | |
| Body Features | | |
| Primary Product Color | Natural | |

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Contact Features

| Contact Layout | Staggered | |
|---|-----------------------------------|--|
| PCB Contact Termination Area Plating Material Thickness | 2 μm[80 μin] | |
| Contact Underplating Material Thickness | 1.27 – 2.7 μm[50 – 106 μin] | |
| Contact Mating Area Plating Material Thickness | 2 µm[80 µin] | |
| PCB Contact Termination Area Plating Material Finish | Matte | |
| Contact Mating Area Plating Material Finish | Matte | |
| Contact Underplating Material | Nickel | |
| PCB Contact Termination Area Plating Material | Tin | |
| Contact Base Material | Brass | |
| Contact Mating Area Plating Material | Tin | |
| Contact Type | Pin | |
| Contact Current Rating (Max) | 3 A | |
| Termination Features | | |
| Termination Method to Printed Circuit Board | Surface Mount | |
| Mechanical Attachment | | |
| Mating Alignment Type | Polarization | |
| Mating Retention | With | |
| PCB Mount Retention Type | Solder Peg | |
| Mating Retention Type | Latch | |
| Connector Mounting Type | Board Mount | |
| Mating Alignment | With | |
| PCB Mount Alignment | Without | |
| PCB Mount Retention | With | |
| Housing Features | | |
| Mating Entry Location | Тор | |
| Housing Material | LCP | |
| Centerline (Pitch) | 1.5 mm[.059 in] | |
| Usage Conditions | | |
| Operating Temperature Range | -40 – 105 °C[-40 – 221 °F] | |
| Operation/Application | | |
| Assembly Process Feature | Pick and Place Cover, Plastic Cap | |
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| Circuit Application | Power & Signal | |
|---|---|--|
| Industry Standards | | |
| UL Flammability Rating | UL 94V-0 | |
| Packaging Features | | |
| Packaging Quantity | 950 | |
| Packaging Type | Carton, Reel | |
| | | |
| | | |
| EU RoHS Directive 2011/65/EU | Compliant with Exemptions | |
| EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC | Compliant with Exemptions Not Yet Reviewed | |
| | | |

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Not reviewed for solder process capability

Solder Process Capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

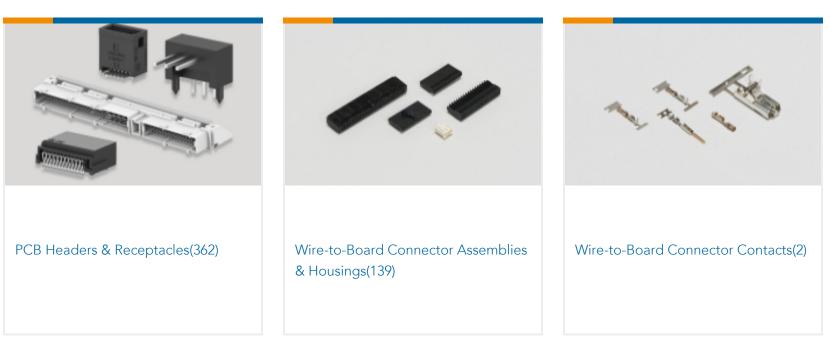
Compatible Parts

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Also in the Series | HPI



Customers Also Bought



| TE Part #2-1623795-3 SQP2 R047 5% WIRE | TE Part #1-1630019-4 HSC200 2K4 5% | TE Part #9-2176397-4 3502 7K5 1% | TE Part #1-1969694-4 PTL 1X4 PCB HEADER R/A HITEMP KEY A LGR |
|---|--|---|--|
| | | | |
| TE Part #YDTS24T15-18PNV001 RECP ASSY | TE Part #YDTS24T21-35SNV001 RECP ASSY | TE Part #YACT24ME35PNV00100 JAM NUT RECEPTACLE | TE Part #YD369-B99-AP400000 369 9 WAY PANEL MNT REC, 90 PCB GOLD,PIN |



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Documents

Product Drawings 1.5P 11POS WTB VERT BRD W LATCH TIN NAT

English

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_1-2380320-1_1.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1-2380320-1_1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-2380320-1_1.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Product Specification

English